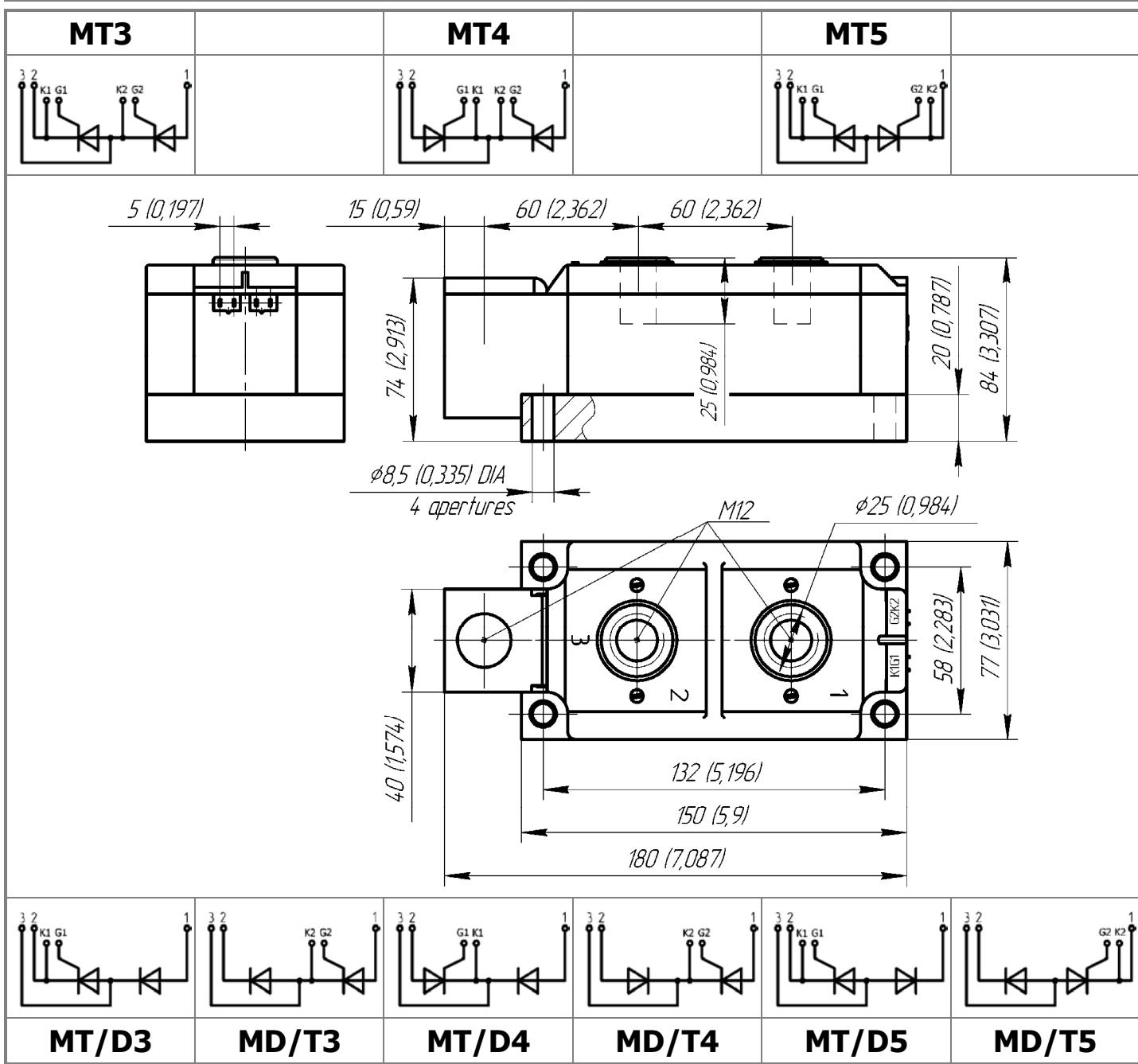




Thyristor / Diode Modules



Mean on-state current	I_{TAV}	630 A
Repetitive peak off-state voltage	V_{DRM}	2600 ÷ 2800 V
Repetitive peak reverse voltage	V_{RRM}	
Turn-off time	t_q	320 μ s
V_{DRM} , V_{RRM} , V	2600	2800
Voltage code	26	28
T_j , °C	-40 ÷ 125	



MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I_{TAV}	Mean on-state current	A	630 580	$T_c=80\text{ }^\circ\text{C}$; $T_c=85\text{ }^\circ\text{C}$; 180° half-sine wave; 50 Hz	
I_{TRMS}	RMS on-state current	A	985	$T_c=80\text{ }^\circ\text{C}$; 180° half-sine wave; 50 Hz	
I_{TSM}	Surge on-state current	kA	21.0 24.0	$T_j=T_{j\max}$ $T_j=25\text{ }^\circ\text{C}$	180° half-sine wave; 50 Hz ($t_p=10\text{ ms}$); single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt \geq 1\text{ A}/\mu\text{s}$
			23.0 26.0	$T_j=T_{j\max}$ $T_j=25\text{ }^\circ\text{C}$	180° half-sine wave; 60 Hz ($t_p=8.3\text{ ms}$); single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt \geq 1\text{ A}/\mu\text{s}$
I^2t	Safety factor	$\text{A}^2\text{s}\cdot 10^3$	2205 2880	$T_j=T_{j\max}$ $T_j=25\text{ }^\circ\text{C}$	180° half-sine wave; 50 Hz ($t_p=10\text{ ms}$); single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt \geq 1\text{ A}/\mu\text{s}$
			2195 2805	$T_j=T_{j\max}$ $T_j=25\text{ }^\circ\text{C}$	180° half-sine wave; 60 Hz ($t_p=8.3\text{ ms}$); single pulse; $V_D=V_R=0\text{ V}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt \geq 1\text{ A}/\mu\text{s}$
BLOCKING					
V_{DRM}, V_{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	2600÷2800	$T_{j\min} < T_j < T_{j\max}$; 180° half-sine wave; 50 Hz; Gate open	
V_{DSM}, V_{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	2700÷2900	$T_{j\min} < T_j < T_{j\max}$; 180° half-sine wave; 50 Hz; single pulse; Gate open	
V_D, V_R	Direct off-state and Direct reverse voltages	V	$0.75\cdot V_{DRM}$ $0.75\cdot V_{RRM}$	$T_j=T_{j\max}$; Gate open	
TRIGGERING					
I_{FGM}	Peak forward gate current	A	8	$T_j=T_{j\max}$	
V_{RGM}	Peak reverse gate voltage	V	5		
P_G	Gate power dissipation	W	4	$T_j=T_{j\max}$ for DC gate current	
SWITCHING					
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive ($f=1\text{ Hz}$)	$\text{A}/\mu\text{s}$	400	$T_j=T_{j\max}$; $V_D=0.67\cdot V_{DRM}$; $I_{TM}=2 I_{TAV}$; Gate pulse: $I_G=2\text{ A}$; $t_{GP}=50\text{ }\mu\text{s}$; $di_G/dt \geq 1\text{ A}/\mu\text{s}$	
THERMAL					
T_{stg}	Storage temperature	$^\circ\text{C}$	-40 ÷ 125		
T_j	Operating junction temperature	$^\circ\text{C}$	-40 ÷ 125		
MECHANICAL					
a	Acceleration under vibration	m/s^2	50		

CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions		
ON-STATE						
V _{TM}	Peak on-state voltage, max	V	1.40	T _j =25 °C; I _{TM} =1978 A		
V _{T(TO)}	On-state threshold voltage, max	V	0.95	T _j =T _j max; 0.5 π I _{TAV} < I _T < 1.5 π I _{TAV}		
r _T	On-state slope resistance, max	mΩ	0.300	T _j =25 °C; V _D =12 V; Gate pulse: I _G =2 A; t _{GP} =50 μs; di _G /dt≥1 A/μs		
I _L	Latching current, max	mA	1500	T _j =25 °C; V _D =12 V; Gate open		
I _H	Holding current, max	mA	300	T _j =25 °C; V _D =12 V; Gate open		
BLOCKING						
I _{DRM} , I _{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	200	T _j =T _j max; V _D =V _{DRM} ; V _R =V _{RRM}		
(dv _D /dt) _{crit}	Critical rate of rise of off-state voltage, min	V/μs	1000	T _j =T _j max; V _D =0.67 V _{DRM} ; Gate open		
TRIGGERING						
V _{GT}	Gate trigger direct voltage, max	V	4.00 2.50 2.00	T _j = T _j min T _j =25 °C T _j = T _j max	V _D =12 V; I _D =3 A; Direct gate current	
I _{GT}	Gate trigger direct current, max	mA	500 300 200	T _j = T _j min T _j = 25 °C T _j = T _j max		
V _{GD}	Gate non-trigger direct voltage, min	V	0.25	T _j =T _j max; V _D =0.67 V _{DRM} ;	Direct gate current	
I _{GD}	Gate non-trigger direct current, min	mA	10.00	Direct gate current		
SWITCHING						
t _{gd}	Delay time	μs	2.50	T _j =25 °C; V _D =0.4 V _{DRM} ; I _{TM} =I _{TAV} ; Gate pulse: I _G =2 A; t _{GP} =50 μs; di _G /dt≥1 A/μs	180° half-sine wave, 50 Hz	
t _q	Turn-off time, max	μs	320	dv _D /dt=50 V/μs; T _j =T _j max; I _{TM} = I _{TAV} ; di _R /dt=-10 A/μs; V _R =100V; V _D =0.67 V _{DRM} ;		
THERMAL						
R _{thjc}	Thermal resistance, junction to case			180° half-sine wave, 50 Hz		
	per module	°C/W	0.0250			
	per arm	°C/W	0.0500			
R _{thch}	Thermal resistance, case to heatsink			180° half-sine wave, 50 Hz		
	per module	°C/W	0.0080			
	per arm	°C/W	0.0160			
INSULATION						
V _{ISOL}	Insulation test voltage	kV	3.00	Sine wave, 50 Hz; RMS	t=1 min t=1 sec	
			3.60			
MECHANICAL						
M ₁	Mounting torque (M8) ¹⁾	Nm	9.00	Tolerance ± 15%		
M ₂	Terminal connection torque (M12) ¹⁾	Nm	18.00	Tolerance ± 15%		
w	Weight	g	3500			

PART NUMBERING GUIDE	NOTES
<p>MT 3 - 630 - 28 - D - N 1 2 3 4 5 6</p> <p>1. Thyristor module (MT) Thyristor – Diode module (MT/D) Diode – Thyristor module (MD/T)</p> <p>2. Circuit Schematic: 3 – serial connection 4 – common Cathode 5 – common Anode</p> <p>3. Average On-state Current, A</p> <p>4. Voltage Code</p> <p>5. Package Type (M.D)</p> <p>6. Ambient Conditions: N – Normal</p>	<p>¹⁾ The screws must be lubricated</p>